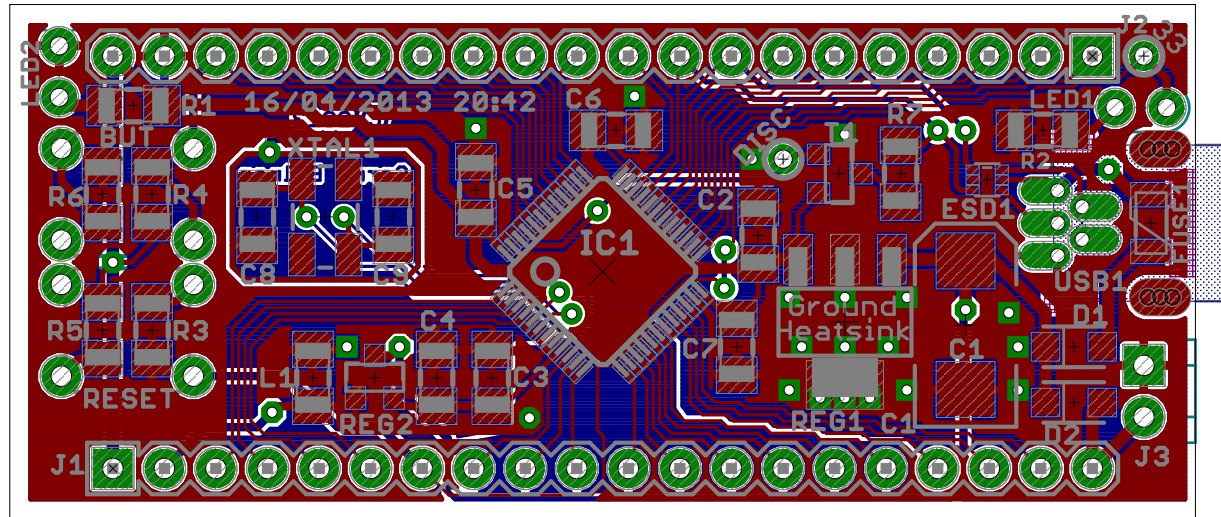


Orone-mini-S8D-v0r001



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40pin 0.8" row spacing

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I ask that my name remain visible in the copper

The pin headers are standard 'breadboard friendly' 0.1" pitch.

The two rows of pin headers are 0.8" apart, and hence fit a single breadboard.

The board is 2.3" long x 1" high. Most components are 1206 or larger.

Notes: 1206 components are too big to fit in mini 2.1" length
Hence the board is lengthened from 2.1" to 2.3" Replaced C1 with 7343-case size
Design Rules: OSHPark.com & Seeedstudio 'Fusion' PCB Service

Routing: Crystal tracks & Top Layer MCU tracks are 6mil/6mil
in order to make enough space for components and isolation.

All tracks from thru-hole (hand soldered) components, except pin headers,
are 10mil or wider. This is intended to make the tracks more robust.

All Bottom Layer tracks are 10mil or bigger, except Crystal tracks;
this is intended to be easier to make.

Copper pours have 10mil isolation; this is intended to be easier to make.

Vias: The three via shapes are used to give information, and help 'read' the PCB.

Via Key: SQUARE: Digital Ground (DGND) and thermal vias

ROUND: Signal

OCTAGON: Power (e.g. Vcc) or segregated Ground (e.g. AGND)

NOTES: There are four Hidden Airwires, which do not need routing (replicated on switches)
For safety, type 'RATSNEST *' to make them visible before making any changes
Two pads 33 and DISC, printed at 45 degrees, are signals, not for components.
DRC->Restricting Pads & Vias minimum increased from OSHPark 7mil to 10mil.